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LOC		DIST		REVISIONS			
P	LTR	DESCRIPTION	DATE	DWN	APVD		
A		ECR-12-003914	29FEB2012	GG	RRP		

NOTES/SPECIFICATION:

- 1 HEADER ACCEPTS TYPES I, II, & III OF PCMCIA STANDARD MEMORY CARD
- 2 MECHANICAL, ELECTRICAL, PLATING, ENVIRONMENTAL SPECIFICATION: CONFIRMS TO PRODUCT REQUIREMENTS AS PER SPECIFICATION 108-19201

3 LENGTH OF CONTACTS:

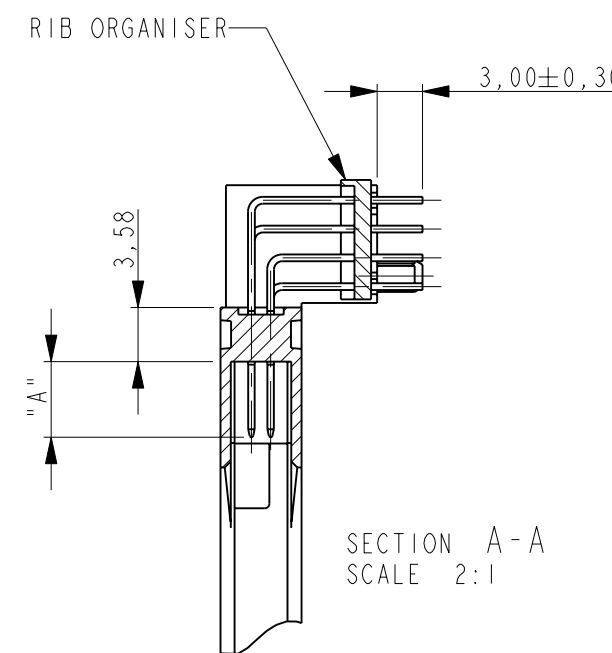
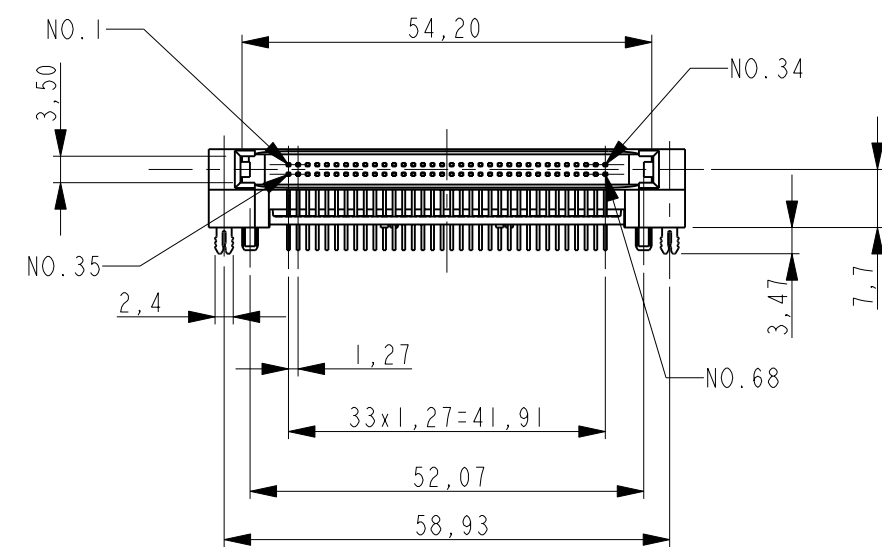
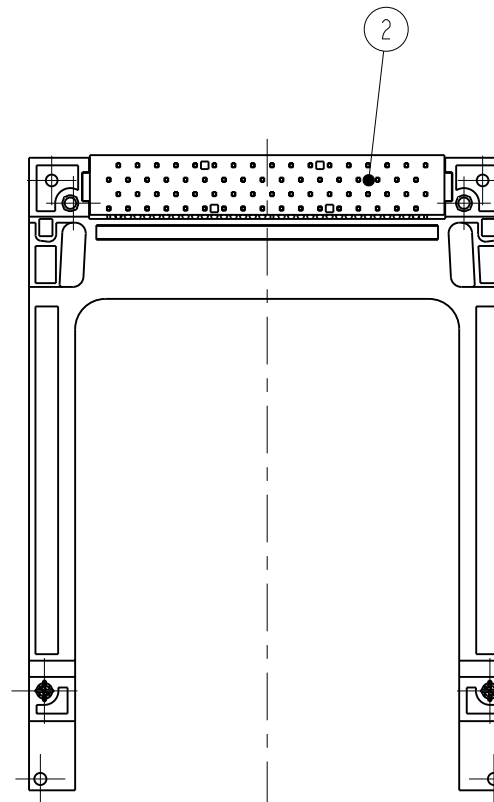
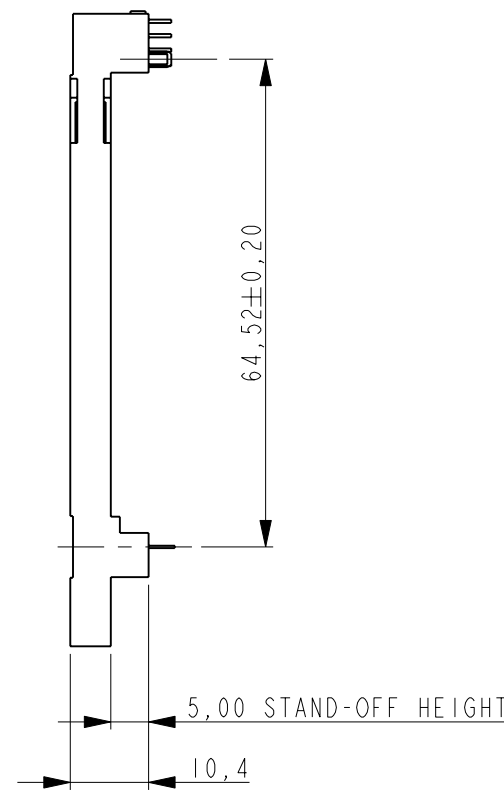
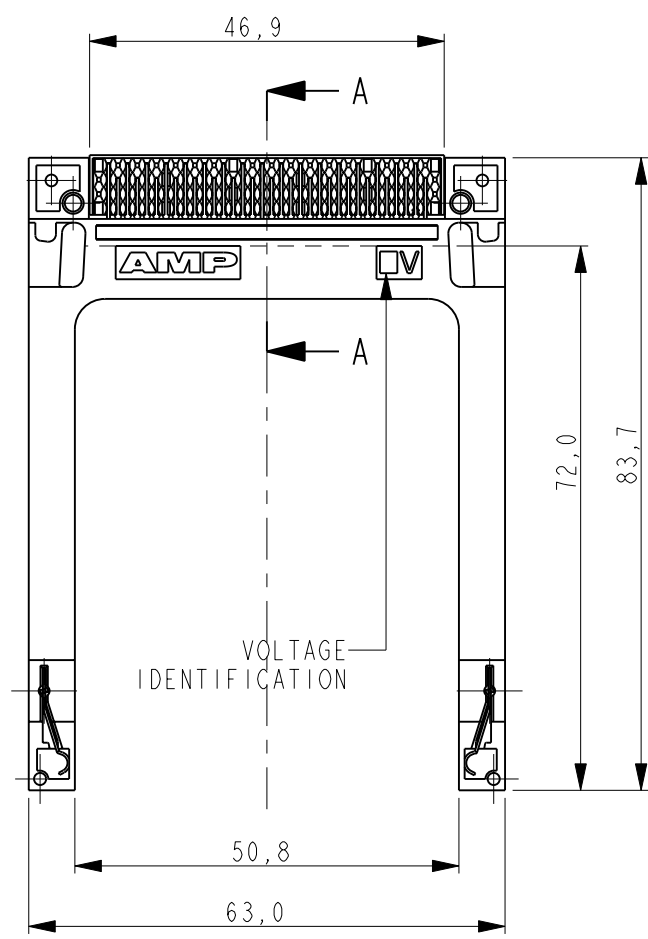
DIM "A"	POSITION No.
5	1, 17, 34, 35, 51, 68
3.5	36, 67
4.25	THE OTHERS

4 PLATING OF CONTACT: Ni: OVERALL  
 Au: CARD SIDE  
 TIN: PCB SIDE

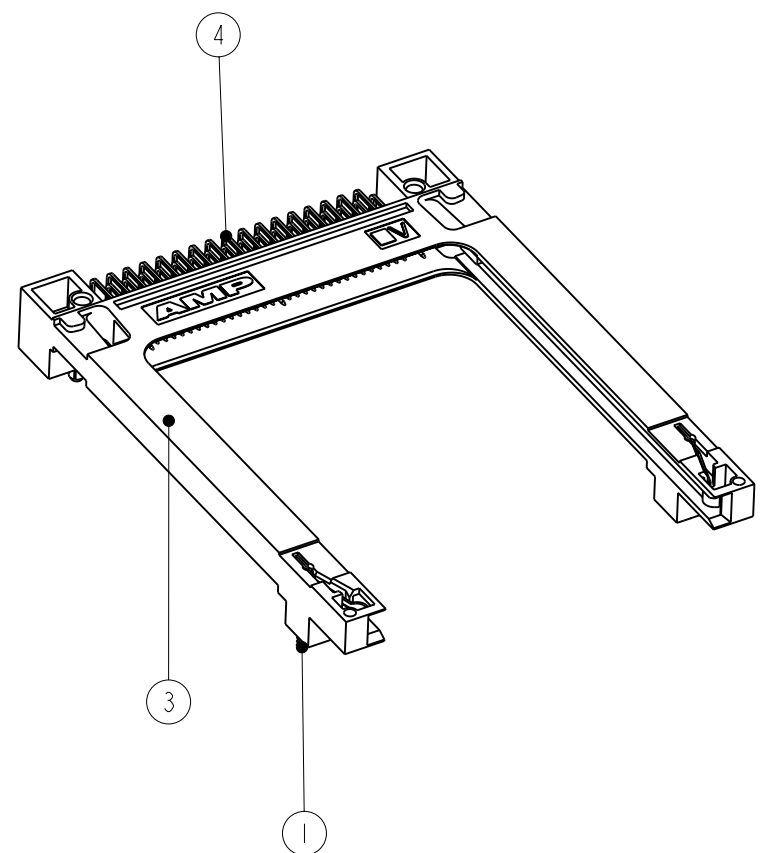
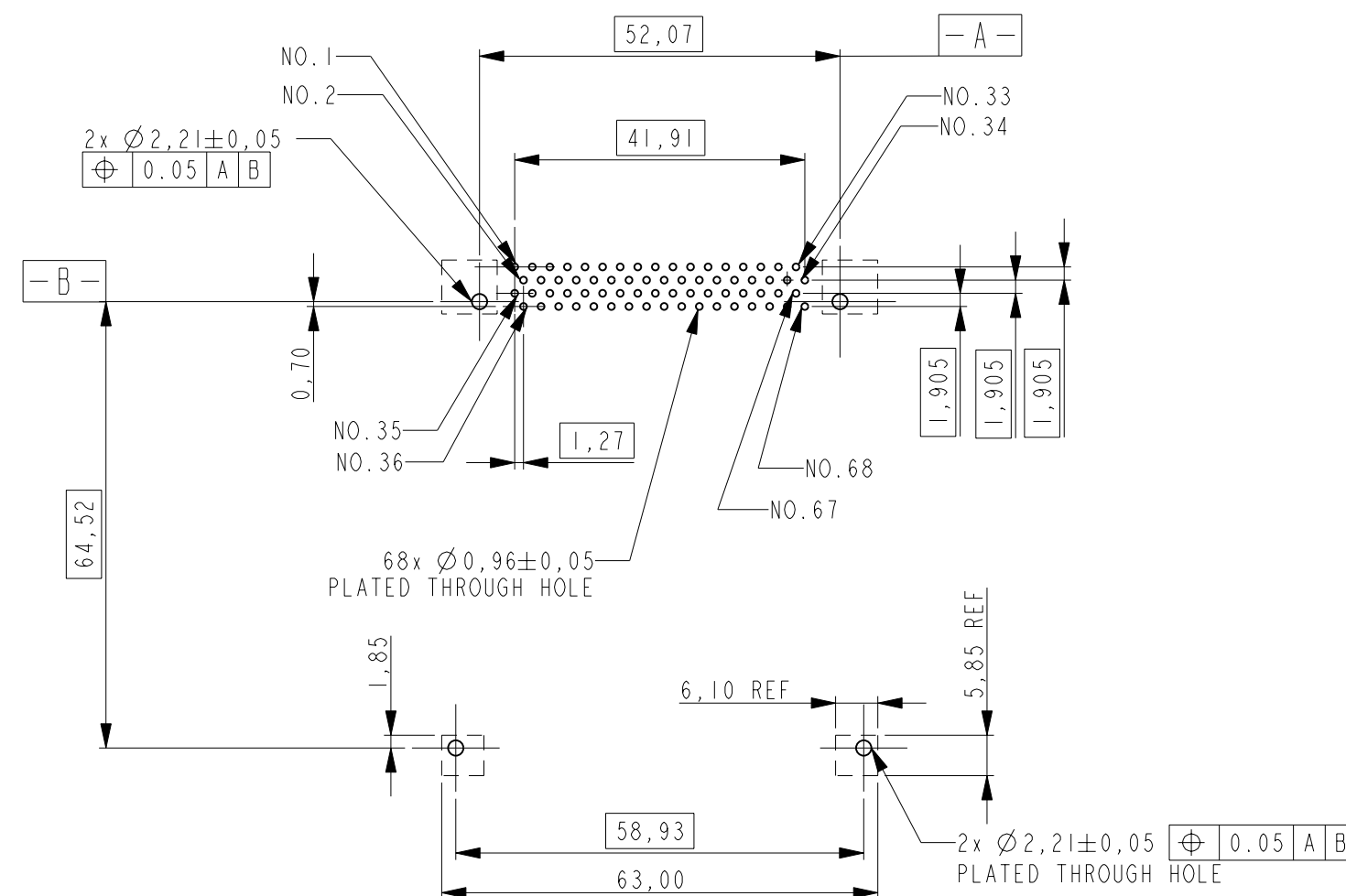
5 ALL PARTS PACKAGED IN TRAYS UNLESS REQUESTED:

CONNECTOR TO PRINTED CIRCUIT BOARD ASSEMBLY:

- 1. PLACE THE CONNECTOR ON THE PRINTED CIRCUIT BOARD. THE SOLDER TAILS, RETENT CLIPS & PLASTIC LEGS SHOULD BE SEATED IN THE RESPECTIVE HOLES.
- 2. PUSH FIRMLY DOWN ON CENTER OF PLASTIC LEGS THEN SOLDER RETENTS. A SLIGHT SNAP IS FELT WHEN THE CONTACT IS FULLY SEATED.
- 3. SOLDER PROCESS ENTIRE PRINTED CIRCUIT BOARD ASSEMBLY.



RECOMMENDED PCB LAYOUT  
 (THICKNESS: 1,60mm ±0,1mm)



2178290-2	3.3V
2178290-1	5.0V
TE PN.	VOLTAGE IDENTIFICATION

ITEM NO	QTY	DESCRIPTION	MATERIAL	FINISH
4	68	CONTACT	COPPER ALLOY	⚠
3	1	HOUSING	THERMOPLASTIC UL94 V0	COLOR: BLACK
2	1	ORGANISER	THERMOPLASTIC UL94 V0	COLOR: BLACK
1	2	GROUND CONTACT	PHOSPHOR BRONZE	TIN

THIS DRAWING IS A CONTROLLED DOCUMENT. DWN: GUNA 23-DEC-11  
 CHK: RAJENDRA 23-DEC-11  
 APVD: RAJENDRA 23-DEC-11

TE Connectivity

PC CARD HEADER HIGH RAISED 5mm  
 0,7mm OFFSET

NAME: PC CARD HEADER HIGH RAISED 5mm 0,7mm OFFSET

SIZE: A2 CAGE CODE: 00779 DRAWING NO: 2178290 RESTRICTED TO: -

MATERIAL: SEE TABLE FINISH: ⚠ WEIGHT: - CUSTOMER DRAWING SCALE: - SHEET: 1 OF 1 REV: A

单击下面可查看定价，库存，交付和生命周期等信息

[>>TE Connectivity\(泰科\)](#)